“Tech-Biz Intelligence”
November 1-4 2022 | Hong Kong Convention & Exhibition Center
Hosted by Hong Kong Section | www.tencon2022.org
Reported by Prof. Kenneth Wong
Conference Schedule

Milestones and Important Dates

- Call for paper: https://www.tencon2022.org/portfolio/paper-submission/
  - Paper submission before July 15
  - Acceptance Date on September 9
  - Template: https://www.ieee.org/conferences/publishing/templates.html
- Inviting distinguished speakers, program and track chairs
- Encouraging sponsors
Conference Organizing Committee

**Honorary Chairs:**
Professor K.J. Ray Liu, IEEE President and CEO 2022
Emeritus Professor A.G. Constantinides, Imperial College London
Dr Nim-kwan Cheung, Chair of IEEE HK 50th Anniversary Celebration

**Honorary Advisors:**
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Emeritus Professor Akinori Nishihara, Immediate Past Director of IEEE R10
Emeritus Professor Lance Chun Che Fung, Director-elect of IEEE R10

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IEEE Hong Kong 50th Anniversary Chair: Dr Nim K Cheung

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Prof Changyuan Yu
Prof Yongxin Guo
Prof Oliver Diessel

**Awards & Recognition Committee:**
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Prof KM Luk
Prof Paul Cheung
Prof PC Ching
Prof Vincent Lau

**Special Sessions, Student Forum & SA Exhibits Co-chairs:**
Paul Hodgson
George Woo
Kevin Lam
George Chan
Dr Tim Woo
Adrian Kwan
Conference Organizing Committee

Special Sessions, Student Forum & SA Exhibits Co-chairs:
Paul Hodgson
George Woo
Kevin Lam
George Chan
Dr Tim Woo
Adrian Kwan

Treasurer & Finance Co-chairs:
Dr Eddy Chiu
George Woo

Sponsorship:
Prof Joseph Ng
Dr Ray Cheung
Dr Albert Lam
Dr Paulina Chan

Industry Liaison:
Dr Albert Lam
Dr Eddy Chiu

General Secretaries:
Dr Jean Lai
Prof Joseph Ng

Website:
Dr Ray Cheung
MATE

Publications (IEEE Xplore):
Dr Gary Wong
Dr Jeff Tang

Technical Programme Sub-committee
Registration & Payment:
Dr Gary Wong
MATE

Local Arrangements:
Dr Kevin Hung
HK Tourism Board

Publicity:
TENCON 2022 Secretariat
IEEE Hong Kong Section ExCom
IEEE Corporate Communications
IEEE Public Visibility
Thanks to OC Team and student helpers
Keynote Speakers

- Professor Vincent W. S. Chan, the Joan and Irwin Jacobs Chair Professor of EECS, MIT
- Professor Raymond W. Yeung, Choh–Ming Li Professor of Information Engineering, The Chinese University of Hong Kong
- Dr Yuan Yu, President of IEEE Standards Association and Founder of 0xSenses Corporation
- Presidents of Higher Education Institutes in Hong Kong
Special Sessions

IEEE Hong Kong 50th Anniversary
Special Sessions

- IEEE Hong Kong contribution to an IEEE Award
- R10 Philanthropic Initiative
- Professional Home Committee
- Public Visibility Committee
- Diversity & Inclusion Committee
- ComSoc WICE Committee
- Chartered Management Institute
- Pre-university Student STEM Forum
Technical Session

“Tech–Biz Intelligence”

- Paper presentation and panel discussion focusing on:
  - Emerging Technologies
  - Multi-disciplinary R&D
  - Global Perspectives
  - Innovation and Entrepreneurship
  - Social and Humanitarian Impact
  - Industry Engagement
  - SYWL tracks
- 50th anniversary distinguished speaker forum
- Student forum, hackathon and poster presentations
- Workshop and tutorials
- IEEE standards exhibition
- Awards and recognition
Registrant Category

- Total number of IEEE Members: 84
- Total number of non-IEEE Members: 66
- Total number of IEEE Student Members: 95
- Total number of non-IEEE Student Members: 46
- Grand Total: 291
Conference Paper Statistics

Tech-Biz Intelligence Program

• 340 Paper submissions
• 250+ Accepted papers and posters
• 224 Final published papers at IEEE Xplore
• 250+ Registered participants
• 50+ invited tutorials
• 3 plenary keynote talks
<table>
<thead>
<tr>
<th>Country/Region</th>
<th>No. of Papers</th>
</tr>
</thead>
<tbody>
<tr>
<td>Australia</td>
<td>4</td>
</tr>
<tr>
<td>Canada, Taiwan</td>
<td>3</td>
</tr>
<tr>
<td>China</td>
<td>36</td>
</tr>
<tr>
<td>Bangladesh, Singapore, Thailand</td>
<td>5</td>
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<tr>
<td>Hong Kong SAR</td>
<td>79</td>
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<tr>
<td>India</td>
<td>35</td>
</tr>
<tr>
<td>Bahrain, Indonesia, Pakistan, UAE, UK</td>
<td>1</td>
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<tr>
<td>Japan</td>
<td>13</td>
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<tr>
<td>Korea</td>
<td>7</td>
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<tr>
<td>Malaysia, Vietnam</td>
<td>2</td>
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<tr>
<td>Philippines</td>
<td>34</td>
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<tr>
<td>Sri Lanka</td>
<td>6</td>
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</tbody>
</table>
# Conference Financial Overview

A. Expenses (USD)  
B. Revenue (USD)  
C. Surplus (USD)  
D. 70% to IEEE HK Section (USD)  
E. 30% to IEEE R10 (USD)  

<table>
<thead>
<tr>
<th>Description</th>
<th>Amount</th>
</tr>
</thead>
<tbody>
<tr>
<td>Expenses (USD)</td>
<td>224,493.27</td>
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<tr>
<td>Revenue (USD)</td>
<td>213,104.69</td>
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<tr>
<td>Surplus (USD)</td>
<td>11,388.58</td>
</tr>
<tr>
<td>70% to IEEE HK Section (USD)</td>
<td>7,972.01</td>
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<tr>
<td>30% to IEEE R10 (USD)</td>
<td>3,416.57</td>
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Sponsors

Thanks to all sponsors and supporting organizations